

SIM cards assembly process simplified!

Singapore-based smart card innovator NovoFlex announces Secure Authenticable Identification Laminates (sAIL)™, a patented, groundbreaking new process that redefines how integrated circuit (IC) chips will be embedded into SIM cards currently used in the telecommunications sector. NovoFlex is partnering with smart card manufacturer Eastcompeace in India and CIPTA in Indonesia to implement the IC chip in SIM cards issued by major mobile operators in those countries.

As the process is compatible with existing card manufacturing machines, sAIL™ can be immediately integrated into current smart-card assembly processes.

CEO of NovoFlex, Dr. Eric Ng, said: "Our mission at NovoFlex is to provide the enabling technologies to make objects smarter. SAIL allows for secure authentication, and while the immediate application is in telecommunications, the flexibility of this technology enables us to envision possibilities much broader than that. We are very proud to introduce this new technology in India and Indonesia, through our partners, and hope to expand very

quickly beyond telecoms."

Rajnish Giri, Managing Director of Eastcompeace India Pvt Ltd, said: "Eastcompeace prides itself on being an early adopter of innovative new technologies and processes. It demonstrates a remarkable leap forward in the production process of SIM cards.

While initial demand for SAIL is expected from the telecommunications sector, NovoFlex is already working with key industry players to apply the technology to banking cards and is confident that its usage will expand to transportation and Internet of Things (IoT) in the near future.

CEO of
NovoFlex,
Dr. Eric
Ng

